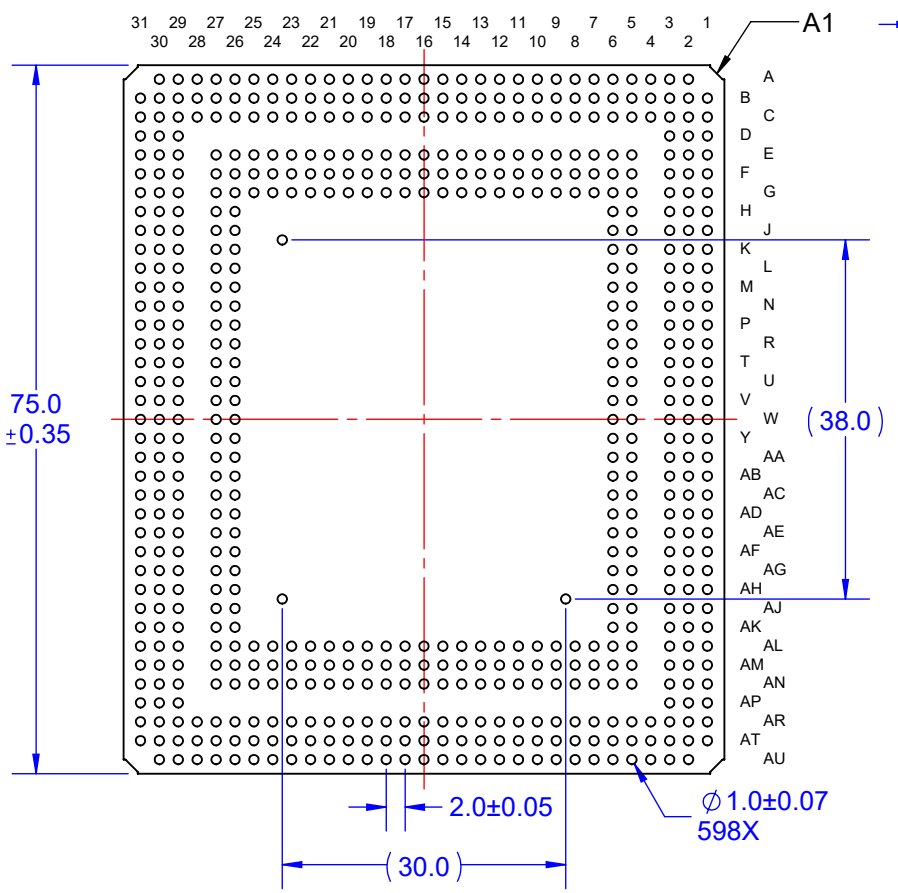
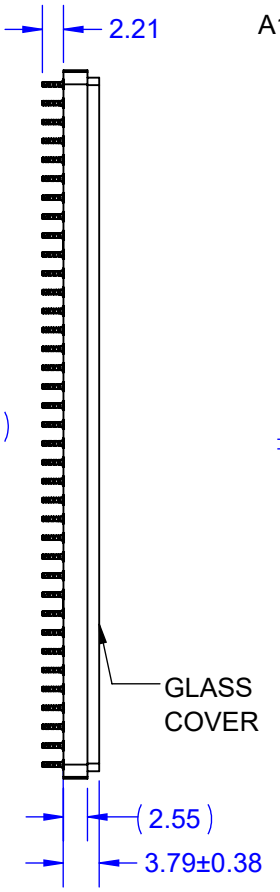
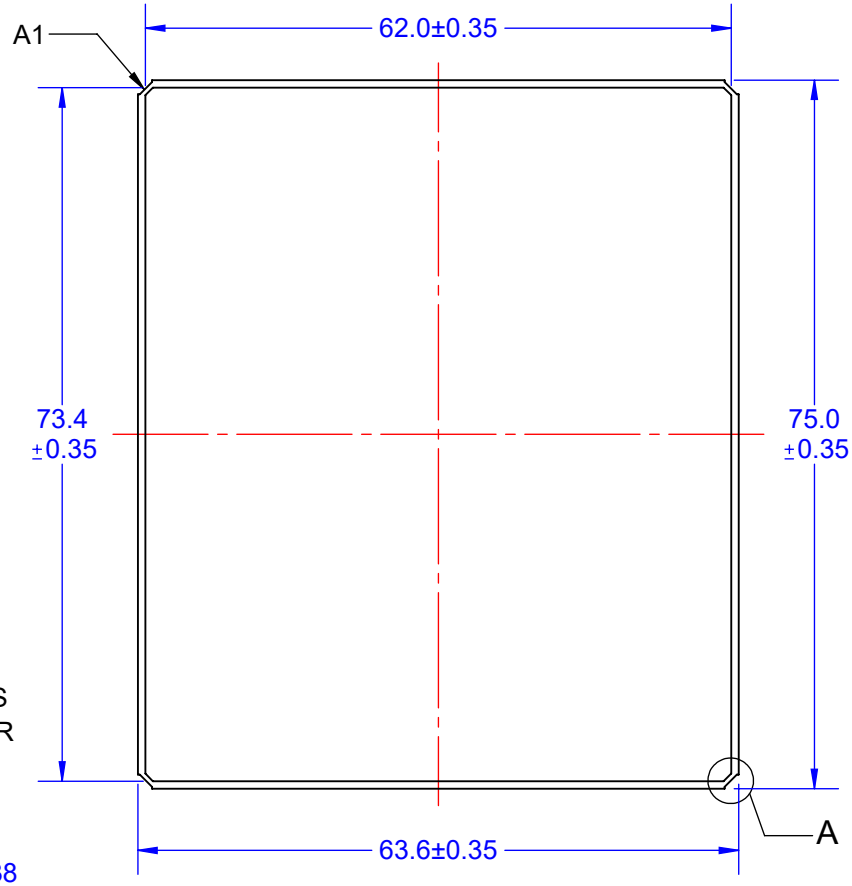
BOTTOM VIEW

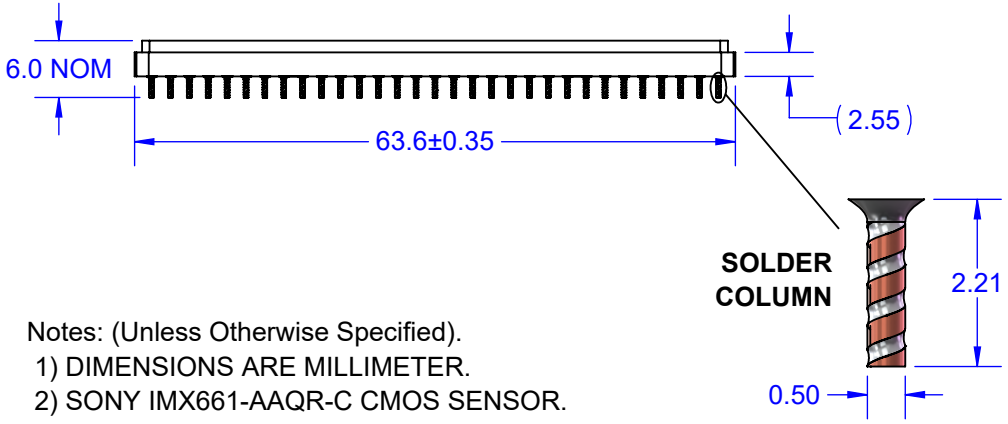


SIDE VIEW



TOP VIEW



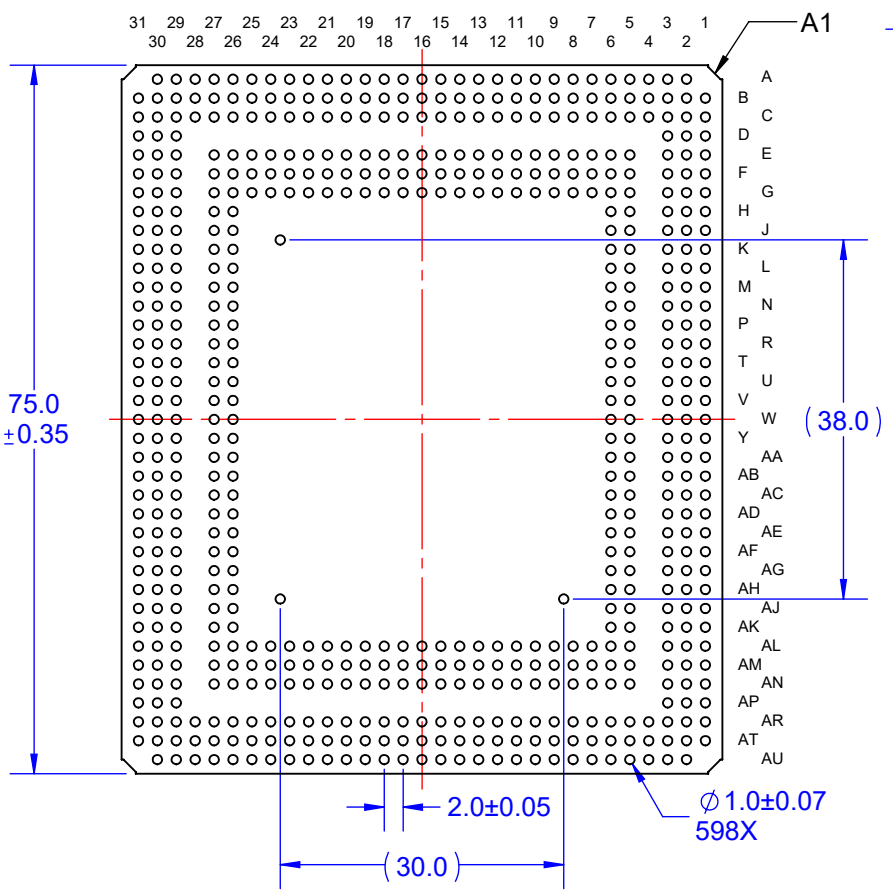


TERMINATIONS:
1) SHOWN WITH Pb80/Sn20 COPPER WRAP COLUMNS.
2) ALTERNATIVE SIZE COLUMNS AVAILABLE.

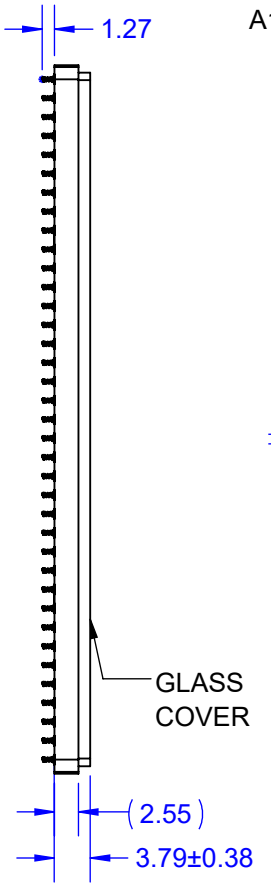
Notes: (Unless Otherwise Specified).
1) DIMENSIONS ARE MILLIMETER.
2) SONY IMX661-AAQR-C CMOS SENSOR.

APPROVALS		DATE	TopLine®			
DRAWN	T.Au	3/12/2021				
ENG	M. Hart	3/12/2021	TITLE	CCGA598 PITCH 2.0mm SONY IMX661		
MFG						
QA			SCALE	SIZE	DRAWING NO.	REV
CUST			1.75:1	A	160085	A
REVISED			DO NOT SCALE DRAWING			SHEET 1 OF 12

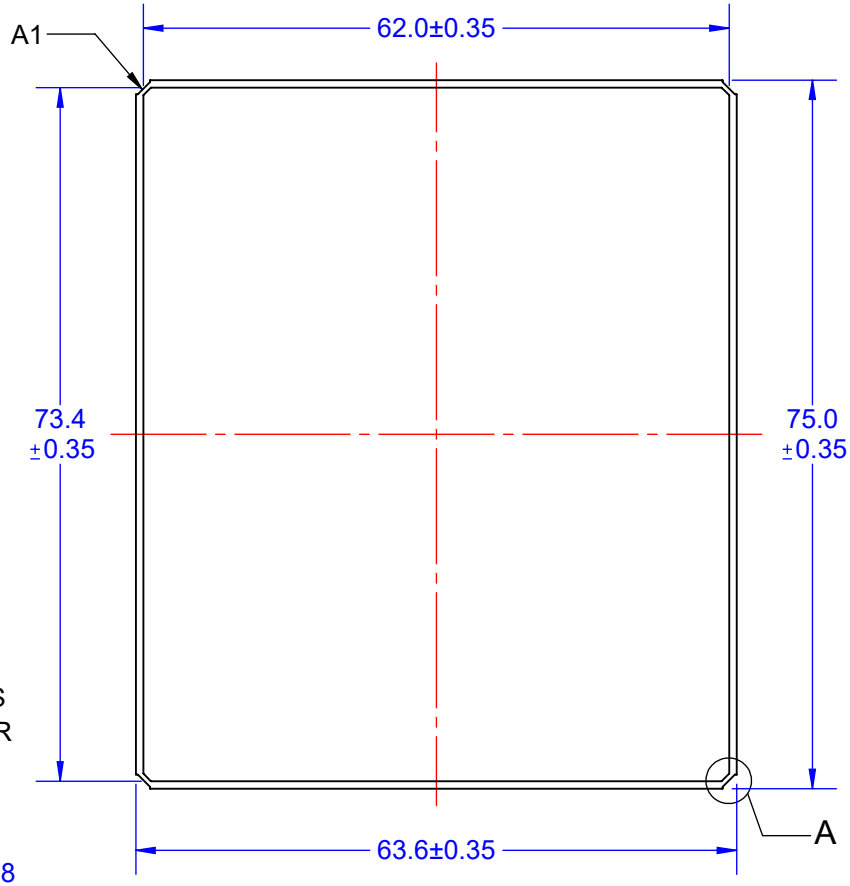
BOTTOM VIEW

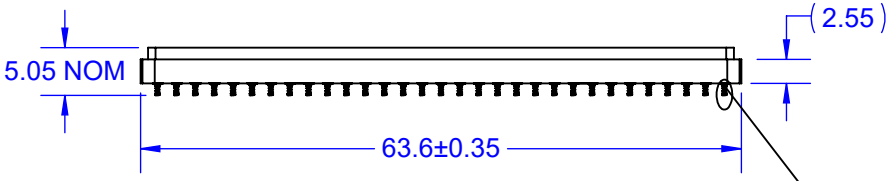


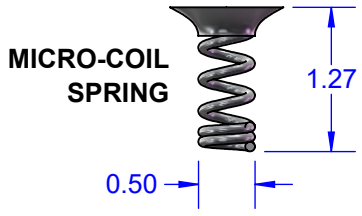
SIDE VIEW



TOP VIEW







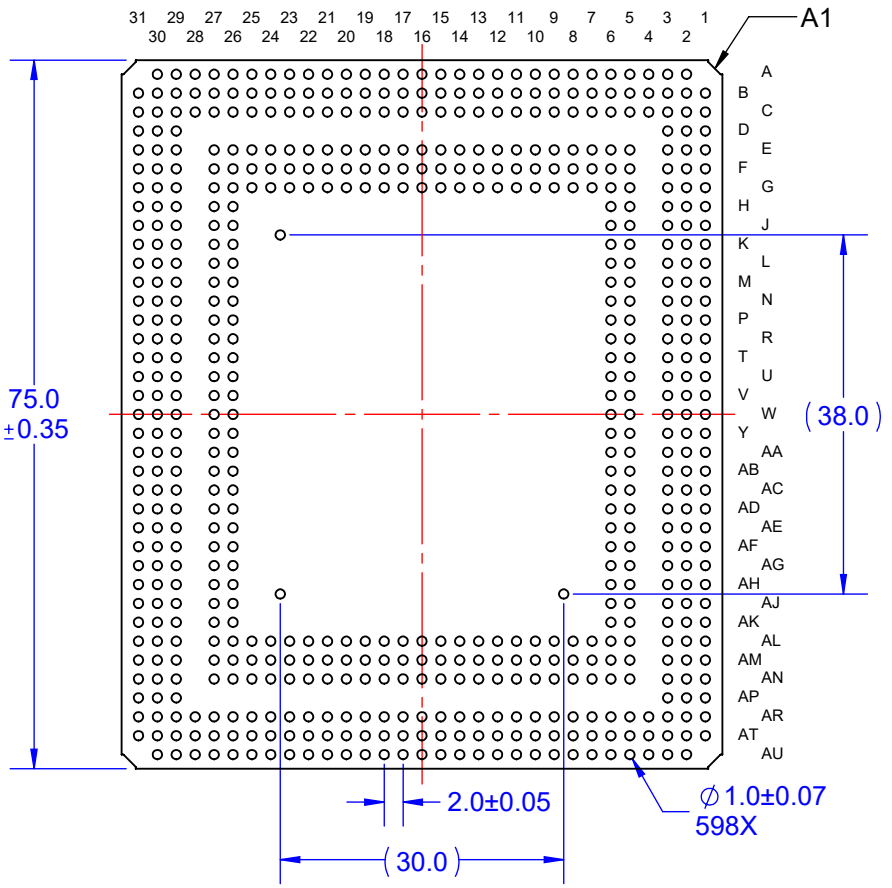
TERMINATIONS:
1) SHOWN WITH MICRO-COIL SPRINGS.
2) ALTERNATIVE SIZE SPRINGS AVAILABLE.

Notes: (Unless Otherwise Specified).
1) DIMENSIONS ARE MILLIMETER.
2) SONY IMX661-AAQR-C CMOS SENSOR.

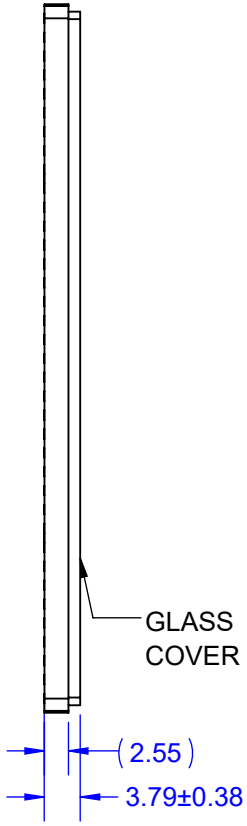
TopLine®

TITLE	CCGA598 PITCH 2.0mm SONY IMX661		
SCALE	SIZE	DRAWING NO.	REV
1.75:1	A	160085	A
DO NOT SCALE DRAWING		SHEET 2 OF 12	

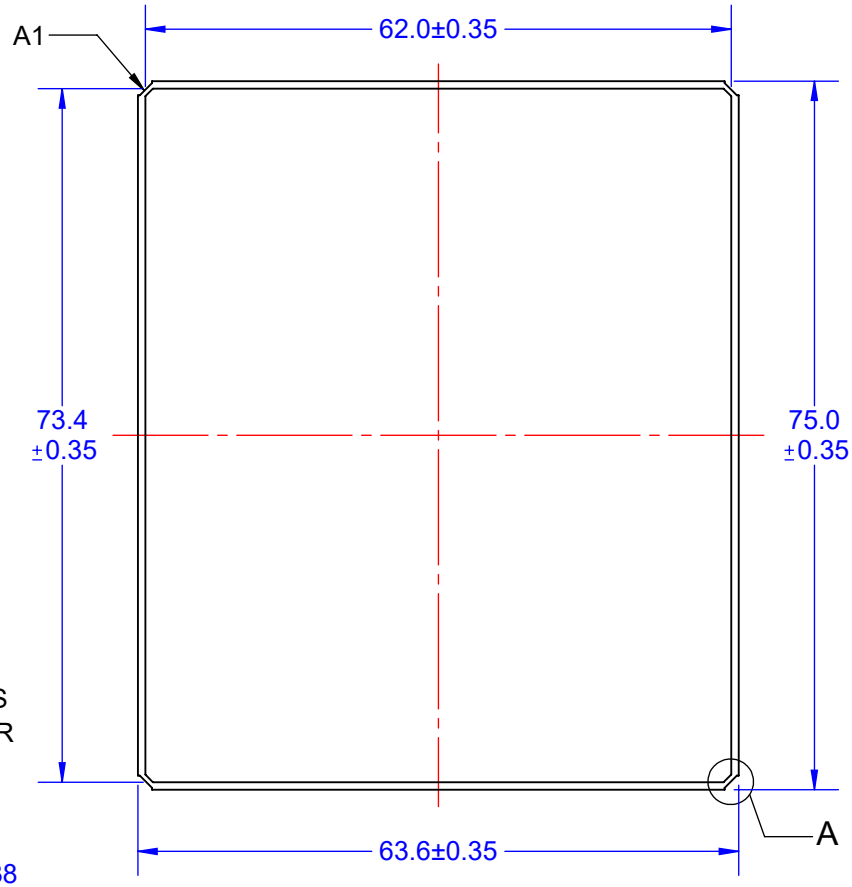
BOTTOM VIEW

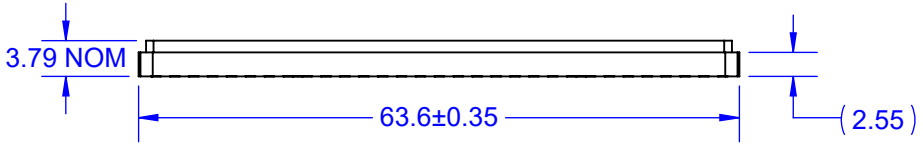


SIDE VIEW



TOP VIEW





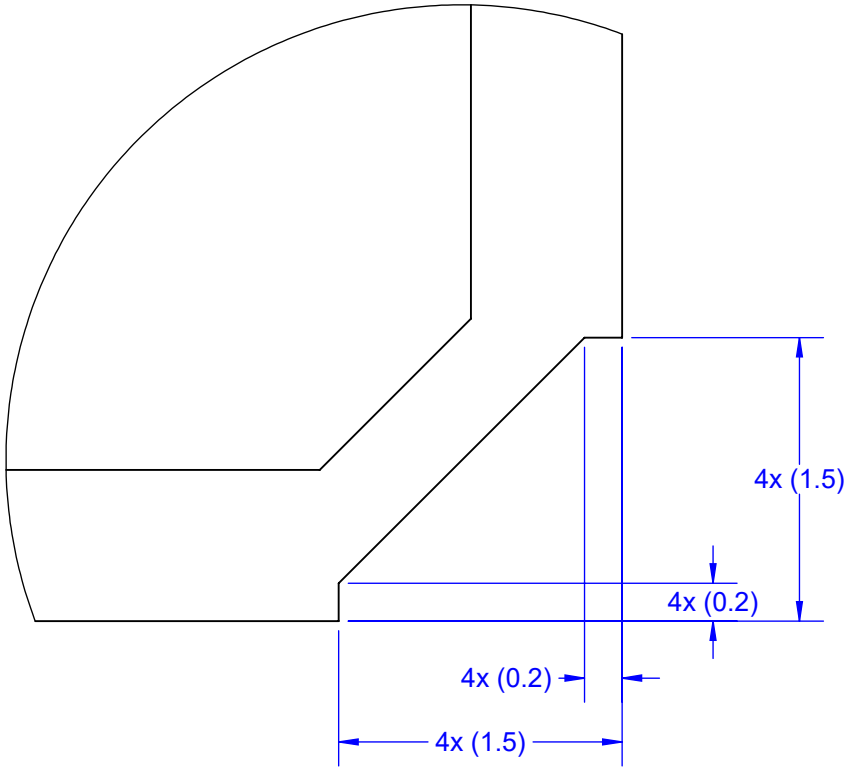
TERMINATIONS:
1) LGA Ni/Au PADS WITHOUT COLUMNS.

Notes: (Unless Otherwise Specified).
1) DIMENSIONS ARE MILLIMETER.
2) SONY IMX661-AAQR-C CMOS SENSOR.

TopLine®

TITLE	CCGA598 PITCH 2.0mm SONY IMX661		
SCALE	SIZE	DRAWING NO.	REV
1.75:1	A	160085	A
DO NOT SCALE DRAWING		SHEET 3 OF 12	

DETAIL A
CORNERS (4X)

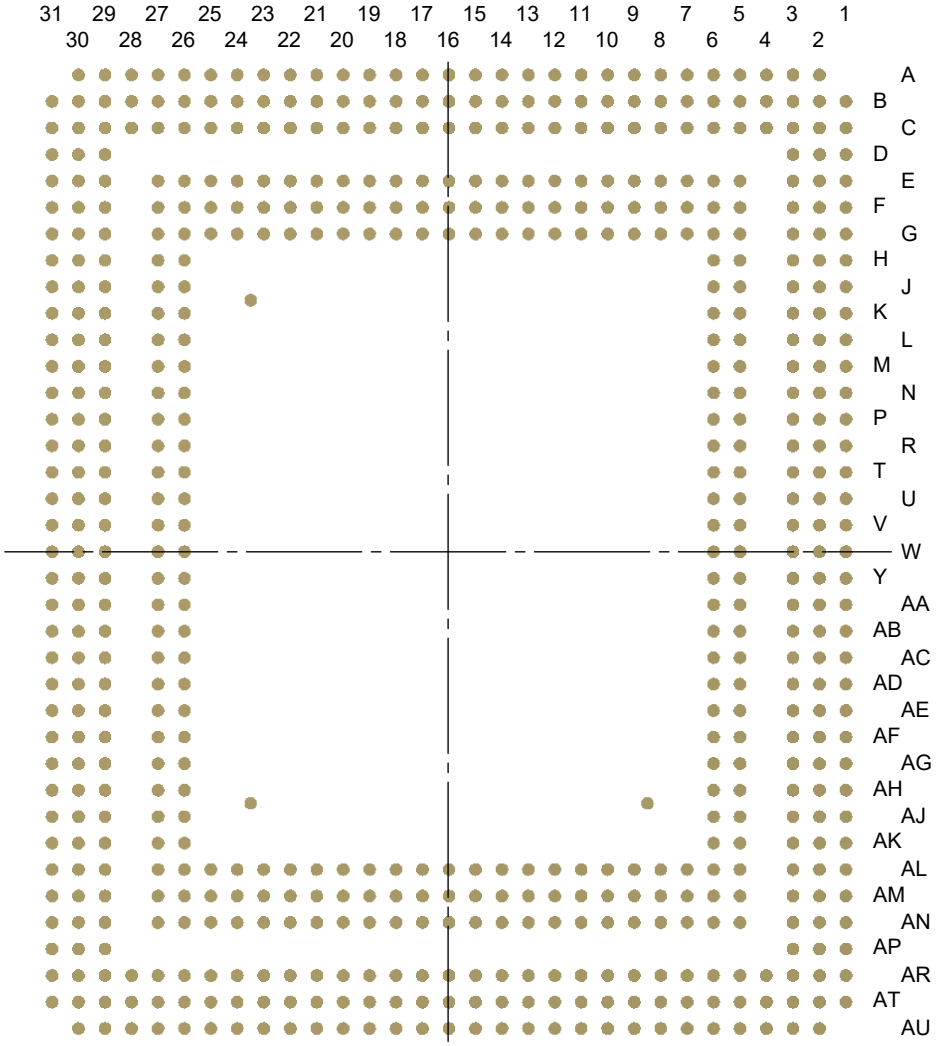


TopLine®

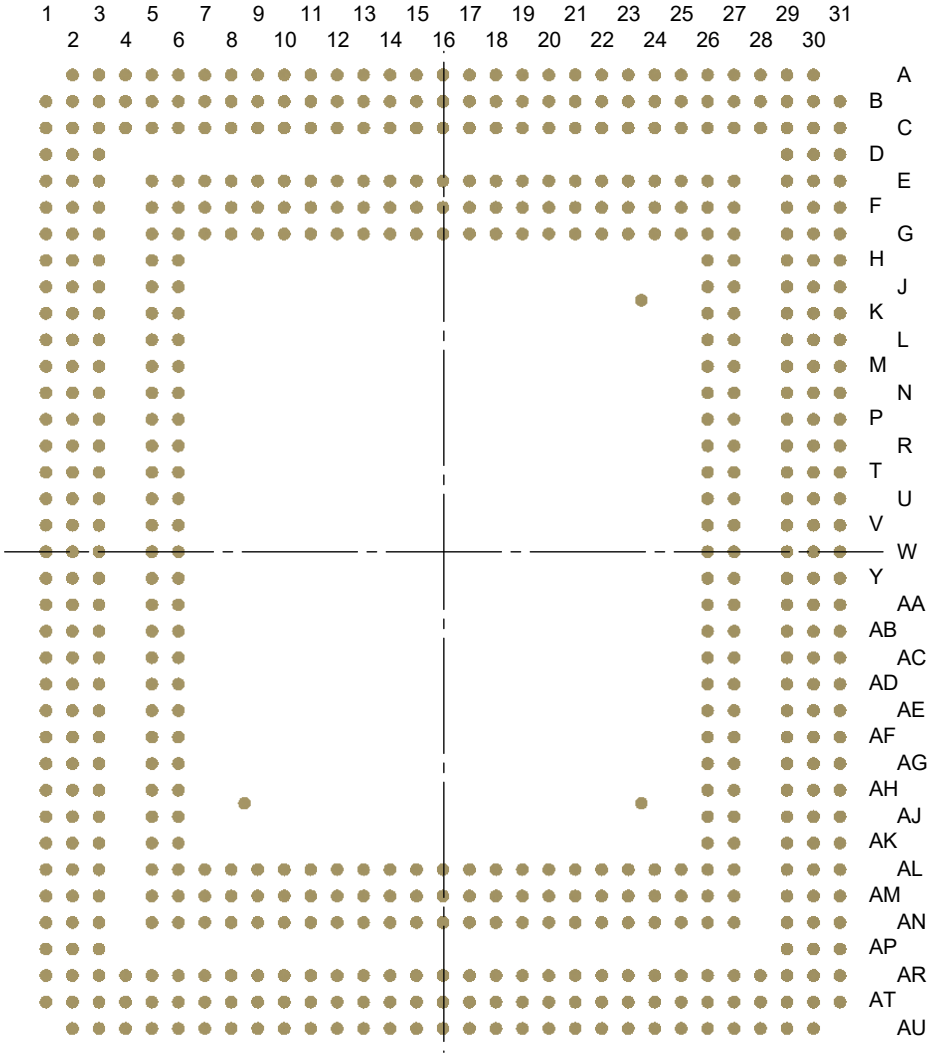
TITLE: CCGA598 PITCH 2.0mm SONY IMX661			
SCALE: 25:1	SIZE: A	DRAWING NO.: 160085	REV: A
DO NOT SCALE DRAWING		SHEET 4 OF 12	

PAD PATTERN

COLUMN (PAD) VIEW



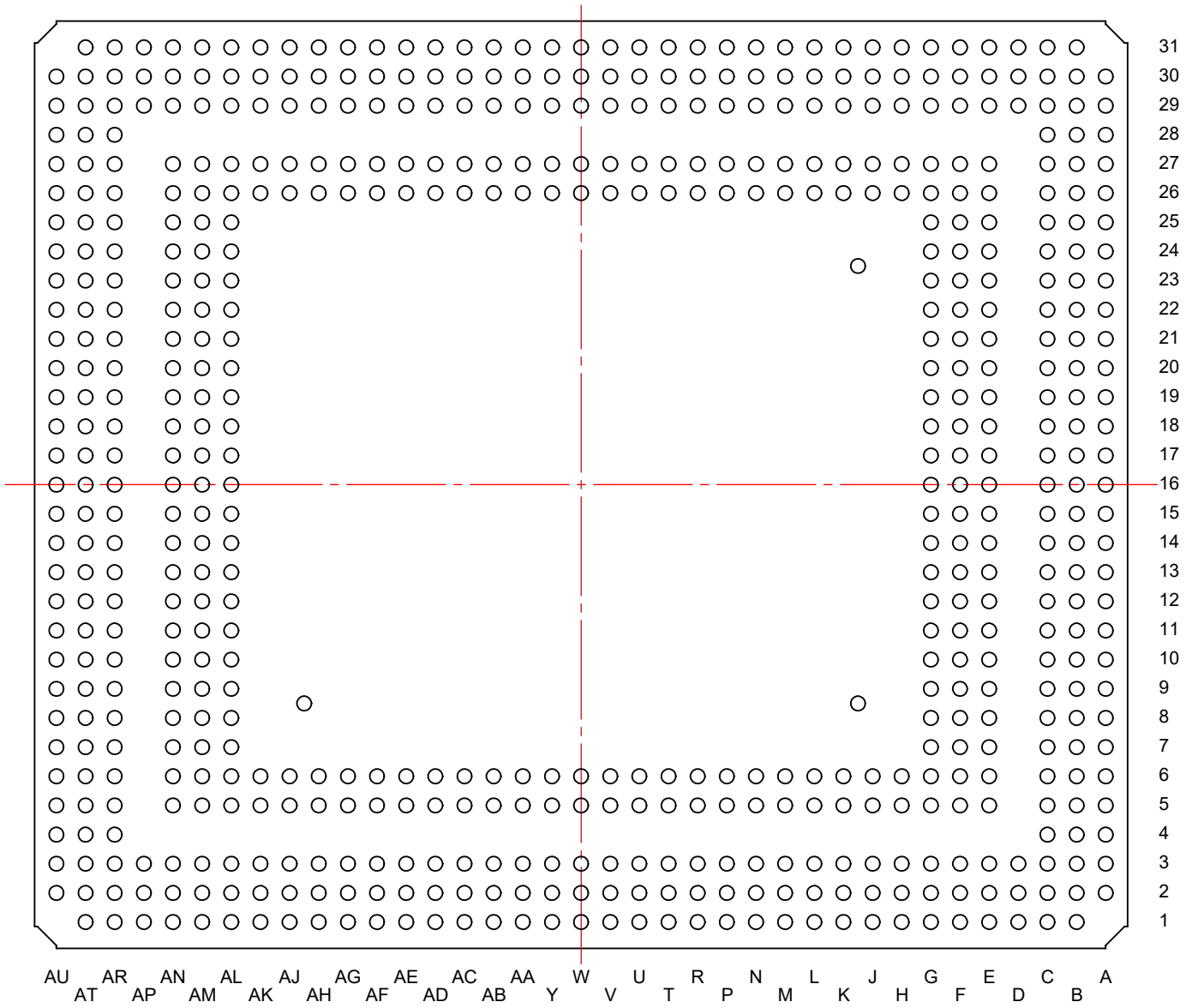
BOTTOM X-RAY VIEW FROM TOP



TopLine®

TITLE: CCGA598 PITCH 2.0mm SONY IMX661			
SCALE: 1.75:1	SIZE: A	DRAWING NO.: 160085	REV: A
DO NOT SCALE DRAWING		SHEET 5 OF 12	

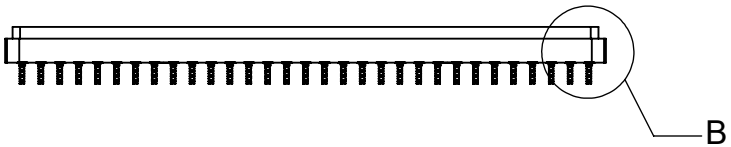
PAD VIEW

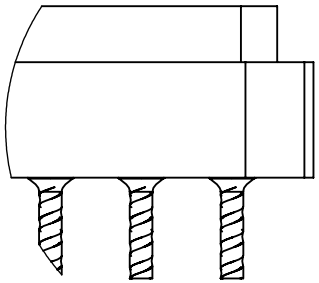


TopLine®

TITLE	CCGA598 PITCH 2.0mm SONY IMX661			
SCALE 2.25:1	SIZE A	DRAWING NO. 160085	REV A	
DO NOT SCALE DRAWING		SHEET 6 OF 12		

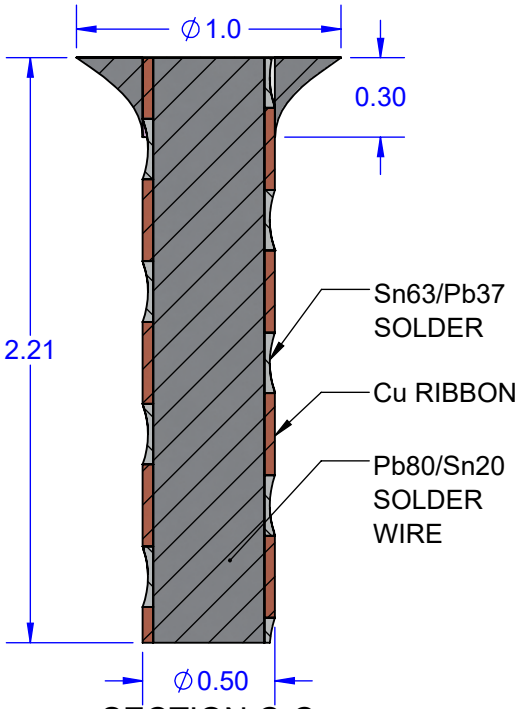
SOLDER PIN OPTIONS





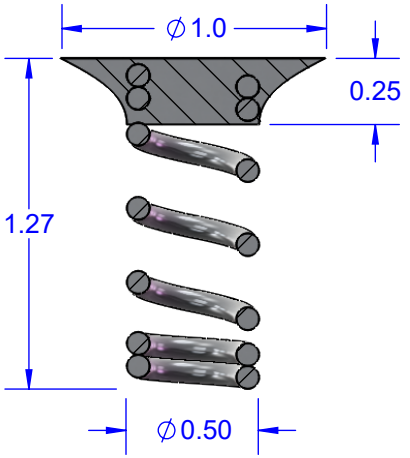
DETAIL B
SCALE 6 : 1

Pb80/Sn20
Cu RIBBON

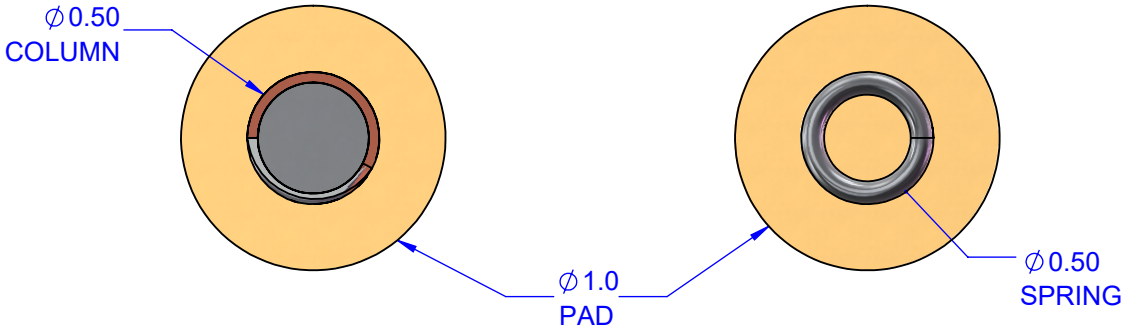


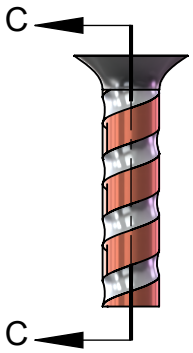
SECTION C-C
SCALE 35 : 1

Micro-coil
Spring

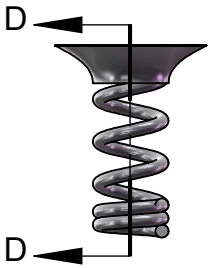


SECTION D-D
SCALE 35 : 1





Pb80/Sn20
Cu RIBBON
SCALE 15:1



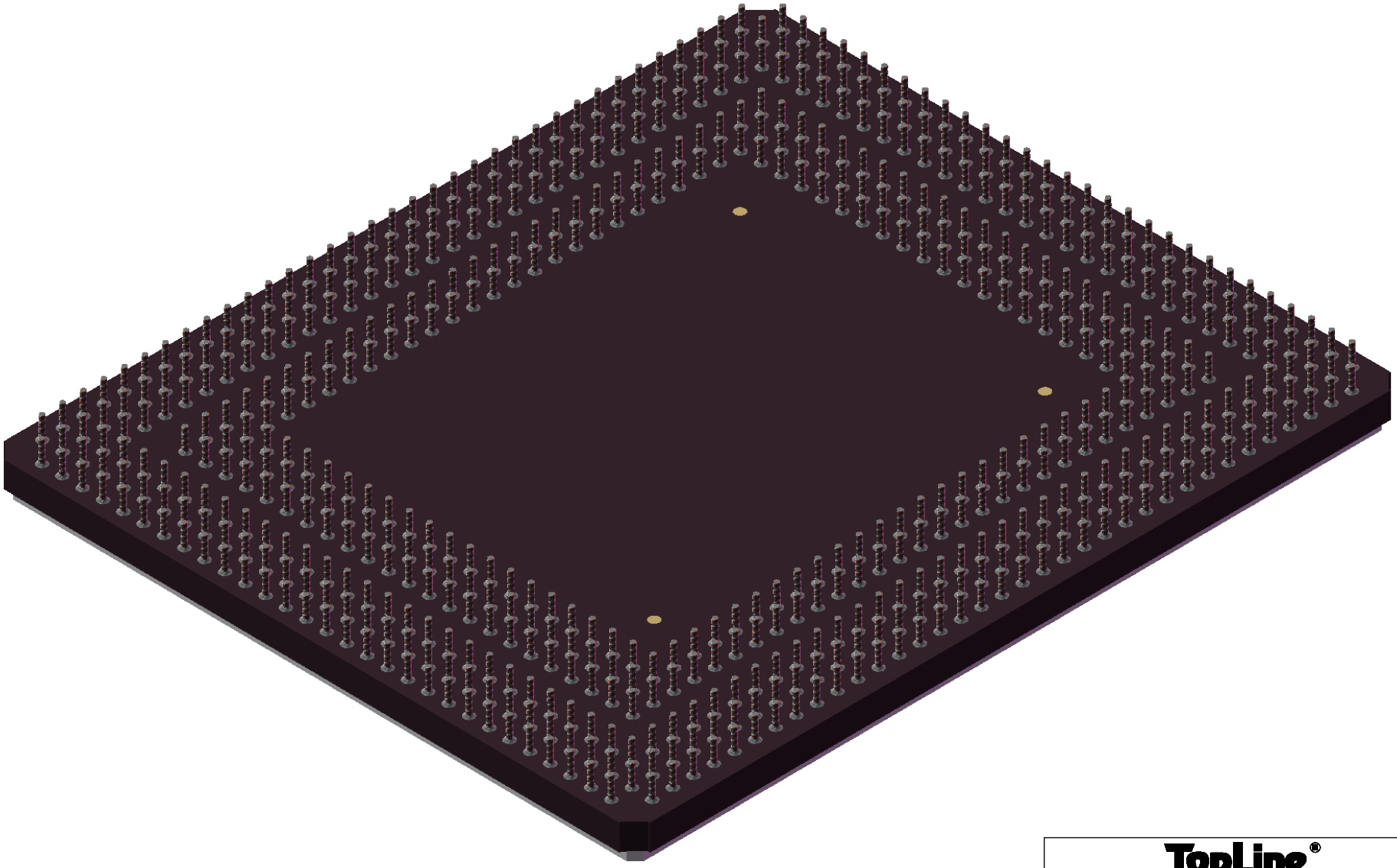
Micro-Coil
Spring
SCALE 20:1

NOTE:
ALTERNATIVE SIZE COLUMNS
AND MICRO-COIL SPRINGS AVAILABLE

TopLine®

TITLE	CCGA598 PITCH 2.0mm SONY IMX661		
SCALE 1.25:1	SIZE A	DRAWING NO. 160085	REV A
DO NOT SCALE DRAWING		SHEET 7 OF 12	

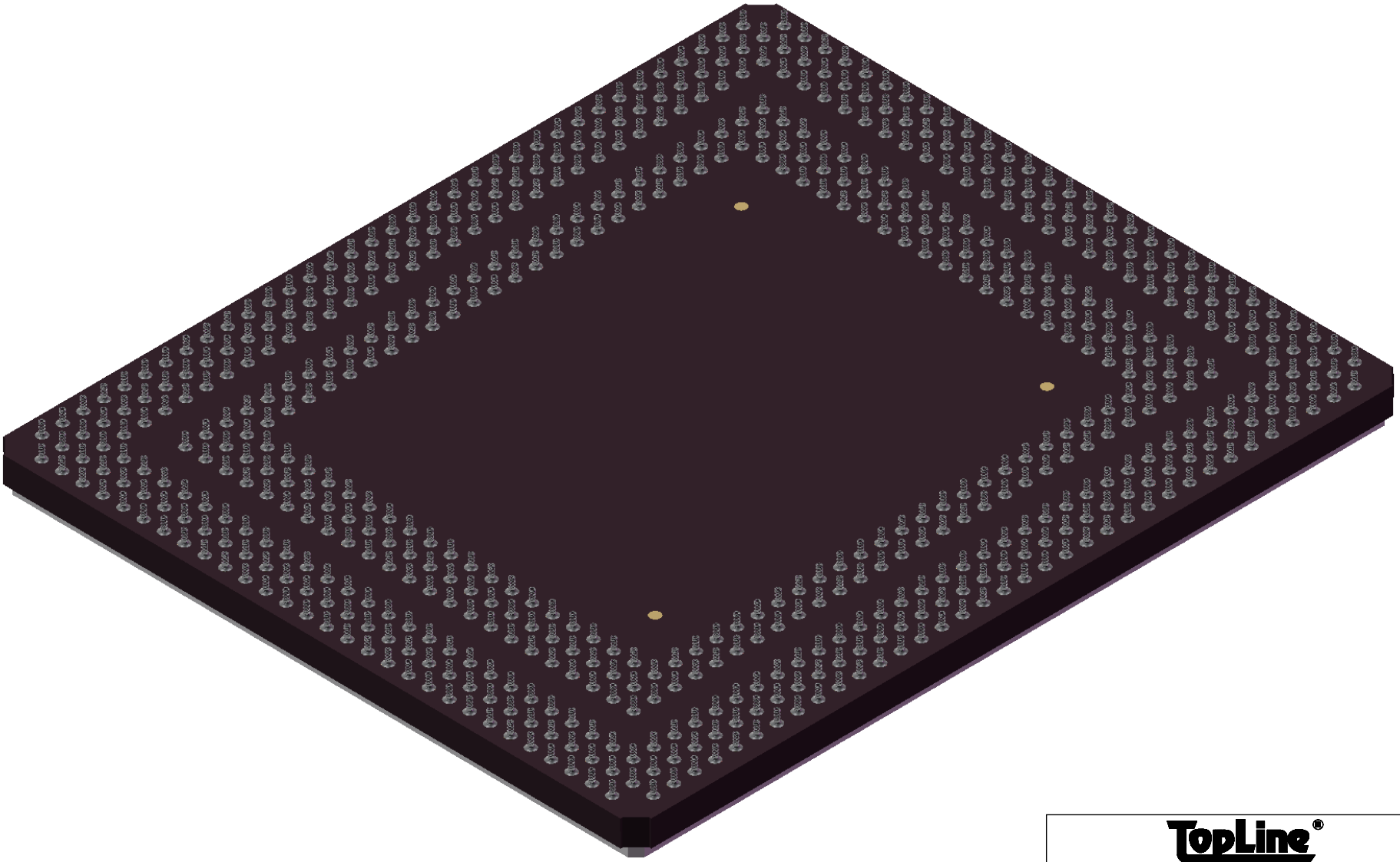
MODEL
Pb80/Sn COLUMNS



TopLine®

TITLE	CCGA598 PITCH 2.0mm SONY IMX661		
SCALE 3:2	SIZE A	DRAWING NO. 160085	REV A
DO NOT SCALE DRAWING		SHEET 8 OF 12	

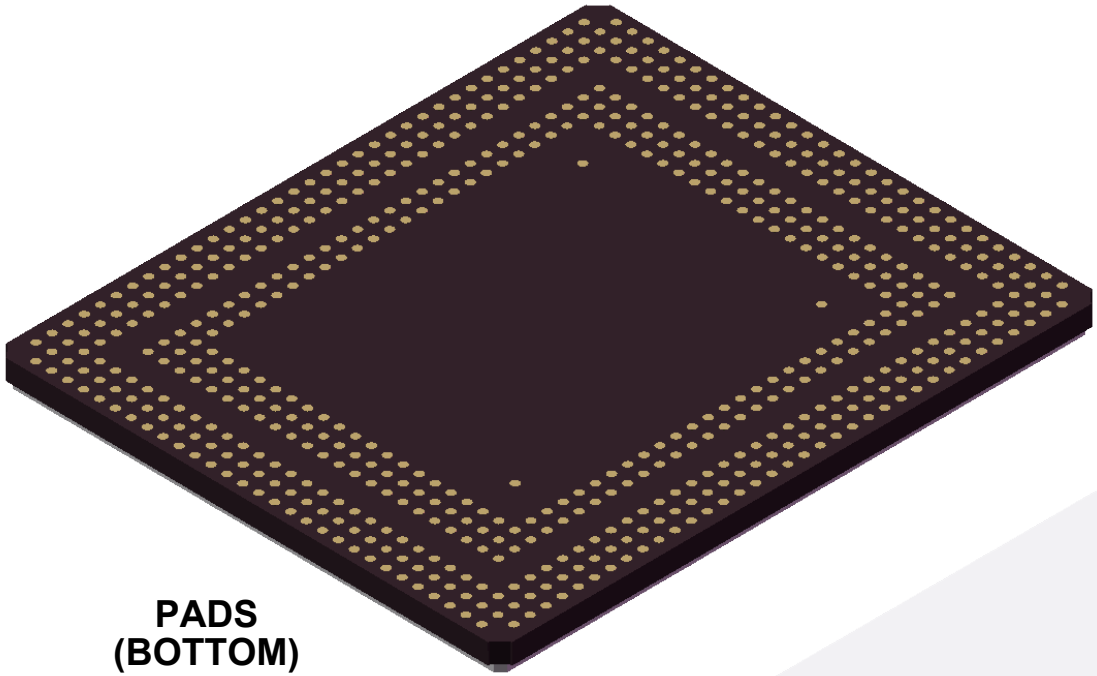
MODEL
MICRO COIL SPRINGS



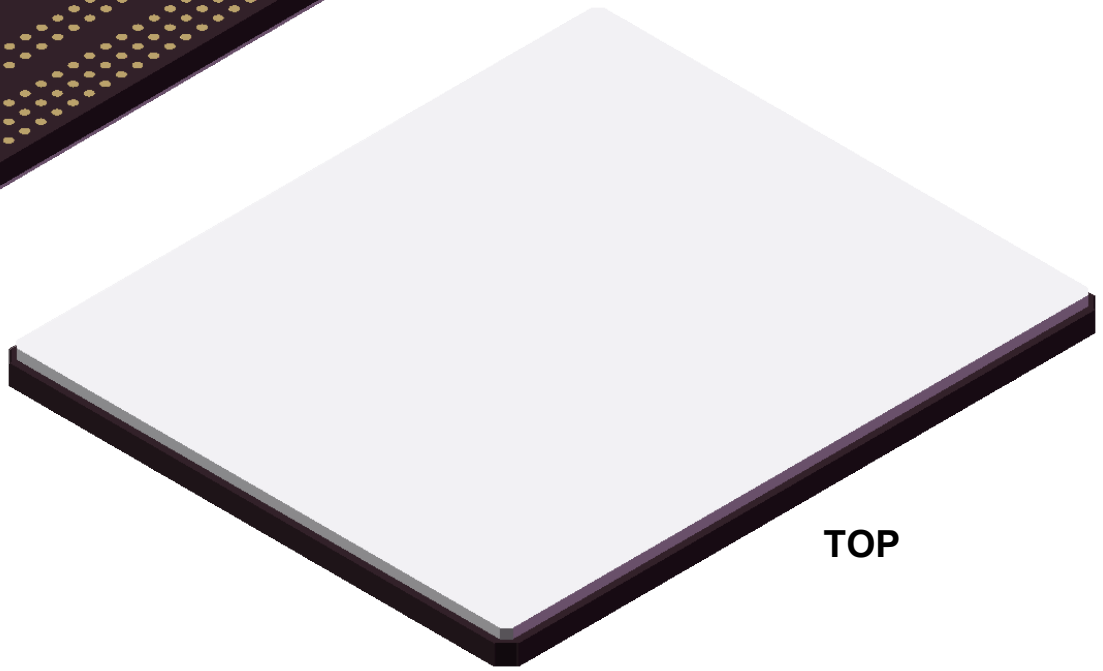
TopLine®

TITLE	CCGA598 PITCH 2.0mm SONY IMX661		
SCALE 3:2	SIZE A	DRAWING NO. 160085	REV A
DO NOT SCALE DRAWING			SHEET 9 OF 12

MODEL



PADS (BOTTOM)



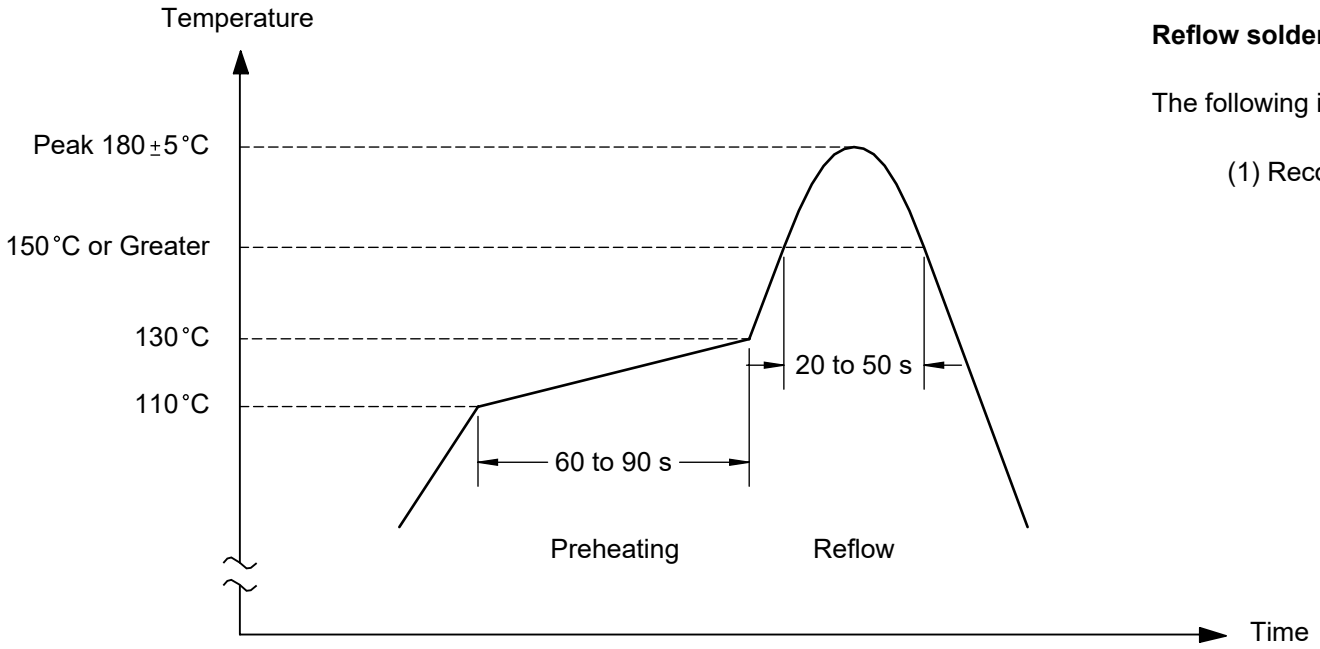
TOP

NOTE:
1) TOP VIEW PRELIMINARY

TopLine®			
TITLE: CCGA598 PITCH 2.0mm SONY IMX661			
SCALE: 3:2	SIZE: A	DRAWING NO.: 160085	REV: A
DO NOT SCALE DRAWING		SHEET 10 OF 12	

REFLOW TEMPERATURE APPLICATION NOTES

Control item	Profile (at part side surface)
1. Preheating	110 to 130˚C 60 to 90 s
2. Temperature up (down)	±4˚C/s or less
3. Reflow temperature	150˚C or Greater 20 to 50 s Max. 5˚C/s
4. Peak temperature	Max. 180 ± 5˚C



Reflow soldering conditions

The following items should be observed for reflow soldering.

(1) Recommended temperature profile for reflow soldering.

TopLine®

TITLE	CCGA598 PITCH 2.0mm SONY IMX661		
SCALE: NONE	SIZE: A	DRAWING NO.: 160085	REV: A
DO NOT SCALE DRAWING			SHEET 11 OF 12

APPLICATION NOTES

(A) Reflow conditions

(1) Maximum temperature of the upper surface of the seal glass resin adhesive portion of the package does not exceed 185°C.

(2) Maximum reflow soldering only one time.

(3) Finish reflow soldering within 72 h after unsealing the degassed packing. Store the products under the condition of temperature of 30°C or less and humidity of 70% RH or less after unsealing the package.

(4) Perform re-baking only one time under the condititon at 125°C for 24 h.

(5) Note that condensation on glass or discoloration on resin interfaces may occur if the actual temperature and time exceed the conditions mentioned above.

(B) Other Notes:

(1) Do not expose to strong light (sun rays) for long periods, as the color filters of color devices will be discolored.

(2) Exposure to high temperature or humidity will affect the characteristics. Accordingly avoid storage or use in such conditions.

(3) This product is precision optical parts, so care should be taken to not apply excessive mechanical shocks or force.

(4) Note that imaging characteristics of the sensor may be affected when approaching strong electromagnetic wave or magnetic field during operation.

(5) Note that image may be affected by the light leaked to optical black when using an infrared cut filter that has transparency in near infrared ray area during shooting subjects with high luminance.

(6) Note that X-ray inspection may damage characteristics of the sensor.

TopLine®

TITLE	CCGA598 PITCH 2.0mm SONY IMX661		
SCALE	SIZE	DRAWING NO.	REV
NONE	A	160085	A
DO NOT SCALE DRAWING			SHEET 12 OF 12